Product Change Notification: DSNO-13APZA934

Date:

15-May-2026

Product Category:

Bluetooth Module

Notification Subject:

CCB 8254 Final Notice: Qualification of U08D as a new fabrication location of Die #2 of catalog part number AT24C64D-XHM-T available in 8L TSSOP (4.4mm) used in the U2 component of BM23SPKS1NB9-YBN3AA, BM23SPKS1NB9-0B02AA, BM23SPKS1NB9-YB03AA, BM23SPKS1NB9-YB02AA, BM23SPKA1NB9-0B02AA, BM23SPKS1NB9-LB01AA, BM23SPKS1NB9-YB01AA, BM23SPKS1NB9-0001AA and BM23SPKA1NB9-0001AA catalog part numbers (CPN) available in 43L MODULE (15x29mm) package.

Affected CPNs:

DSNO-13APZA934_Affected_CPN_05152026.pdf
DSNO-13APZA934_Affected_CPN_05152026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of U08D as a new fabrication location of Die #2 of catalog part number AT24C64D-XHM-T available in 8L TSSOP (4.4mm) used in the U2 component of BM23SPKS1NB9-YBN3AA, BM23SPKS1NB9-0B02AA, BM23SPKS1NB9-YB03AA, BM23SPKS1NB9-YB02AA, BM23SPKA1NB9-0B02AA, BM23SPKS1NB9-LB01AA, BM23SPKS1NB9-YB01AA, BM23SPKS1NB9-0001AA and BM23SPKA1NB9-0001AA catalog part numbers (CPN) available in 43L MODULE (15x29mm) package.

Pre and Post Summary Changes:

*U2 Component	Pre Change	Post Change	Change (Yes/No)

Fabrication Site	Die #1	No change in fabrication site.				No
	Die #2	Microchip Technology Tempe – Fab 2 (TMGR)	Microchip Technology Gresham – Fab 4 (GRTM)	Microchip Technology Colorado (MCSO)	United Microelectronics Corporation (Fab 8D (U08D)	Yes
Wafer Size	Die #1	No change in wafer size.				No
	Die #2	8"	8"	6"	8"	Yes

***Note:** The U2 component (AT24C64D-XHM-T) catalog part number has already been qualified at U08D through PCN# **NTDO-27KWWJ104**.
Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability and on-time delivery performance by qualifying a second fabrication source at United Microelectronics Corporation (Fab 8D) (U08D) site for Die #2 used in the component U2.

Change Implementation Status: In Progress

Estimated First Ship Date: 05 June 2026 (date code: 2623)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	May 2026					**June 2026**				
Work Week	18	19	20	21	22	23	24	25	26	27
Qual Report Availability			x							
Final PCN Issue Date			x							
Estimated Implementation Date						x				

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: May 15, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

Location_of_Component_U2.pdf
PCN_DSNO-13APZA934_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

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